PCN Number: 20190502000.1 May 3, 2019 PCN Date: Title: Transfer of select LMDMOS devices from GFAB to FFAB Wafer Fab site **Customer Contact: PCN Manager** Dept: Quality Services **Estimated Sample** Date provided at **Proposed 1st Ship Date:** Aug 3, 2019 **Availability:** sample request. **Change Type:** Assembly Site Assembly Process Assembly Materials **Electrical Specification** Mechanical Specification Design Packing/Shipping/Labeling Test Process **Test Site** Wafer Bump Site Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials Wafer Fab Process Part number change

PCN Details

Description of Change:

This change notification is to announce the transfer of select LMDMOS devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.

Current Fab Site		New Fab Site			
Current Fab	Process	Wafer	New Fab	Process	Wafer
Site		Diameter	Site		Diameter
GFAB6	LMDMOS	150 mm	FFAB	LMDMOS	200 mm
GFAB8	LMDMOS	200 mm	FFAB	LMDMOS	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Greenock, Scotland (GFAB) Wafer Fab site closure

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock

New Fab Site

FR-BIP-1	TID	DEU	Freising
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483\$12 (P) (2DL) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected Group:

LM2640MTC-ADJ/NOPB	LMD18200T/LF14	LMD18201T	LMD18245T	
LMD18200T	LMD18200T/NOPB	LMD18201T/NOPB	LMD18245T/NOPB	

Qualification Report

Approve Date 24-Apr-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMD18245T/NOPB	QBS Device: LM2675M-5.0/NOPB
AC	Autoclave 121C	96 Hours	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-
HBM	ESD - HBM	2000 V	3/9/0	-
CDM	ESD - CDM	250 V	3/9/0	-
HTOL	Life Test, 125C	1000 HOURS	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 HOURS	-	3/231/0
LU	Latch-up	(per JESD78)	3/18/0	3/18/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0
WLR	Wafer level Reliability	(Per Site Specification)	-	Pass

- Qual Devices qualified at LEVEL1-260CG: LMD18245T/NOPB
- QBS: Qual By Similarity
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- $The following are equivalent HTSL \ options \ based \ on \ an \ activation \ energy \ of \ 0.7eV: 150C/1k \ Hours, \ and \ 170C/420 \ Hours$
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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